

NeXLev™ Connector T-Rise Test Report

Test Report: 04-23A-01

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Test Set-Up

A NeXLev plug and receptacle mated pair housing was loaded with three 10-row wafers along with other unwired wafers; total 30 wafers for the 30-position connector. These three wafers were wired (signal pins) in series and positioned in the center of the connector housings. The center wafer had a thermocouple attached to the A row signal contact pair. A second thermocouple was attached to a J row contact pair. Thermocouples were also attached to the buss wire used to create the series connection and inside the box where the testing was performed. The mated connector pair was set between two pieces of FR4 material to simulate termination to a PCB. The test box prevented any convective airflow around the connector during the test.

The testing described above was repeated with thermocouples attached to a center ground shield of the mated connector.

The test current was applied per EIA-364-70, "Test Procedure for Current vs. Temperature Rise of Electrical Connectors". The plots of the temperature vs. current and the current rating vs. ambient temperature for the signal contact pairs is illustrated in Figures 1 and 2 (maximum permissible ambient temperature = 105°C).

Figure 1

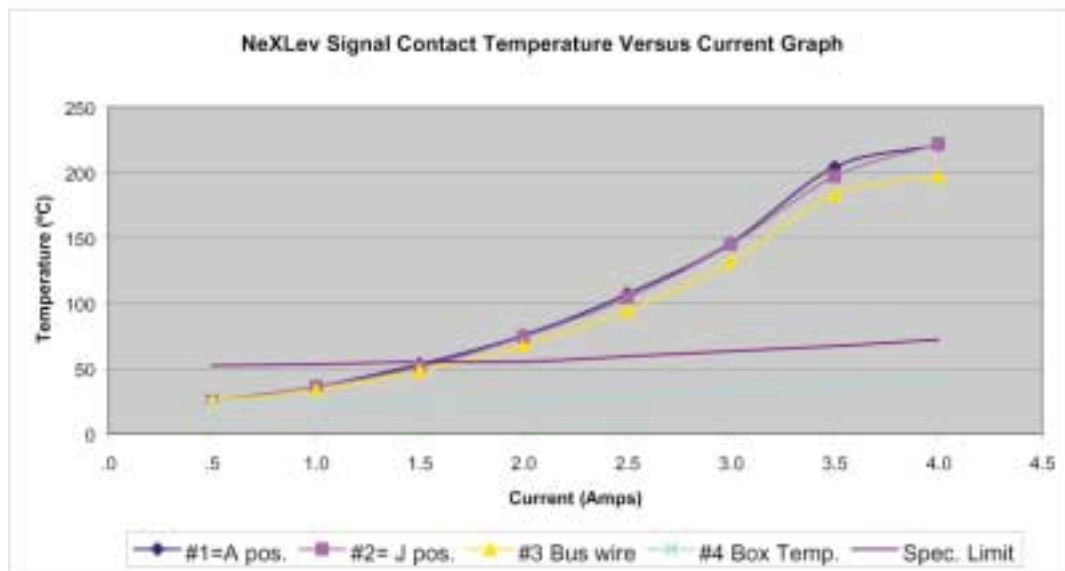
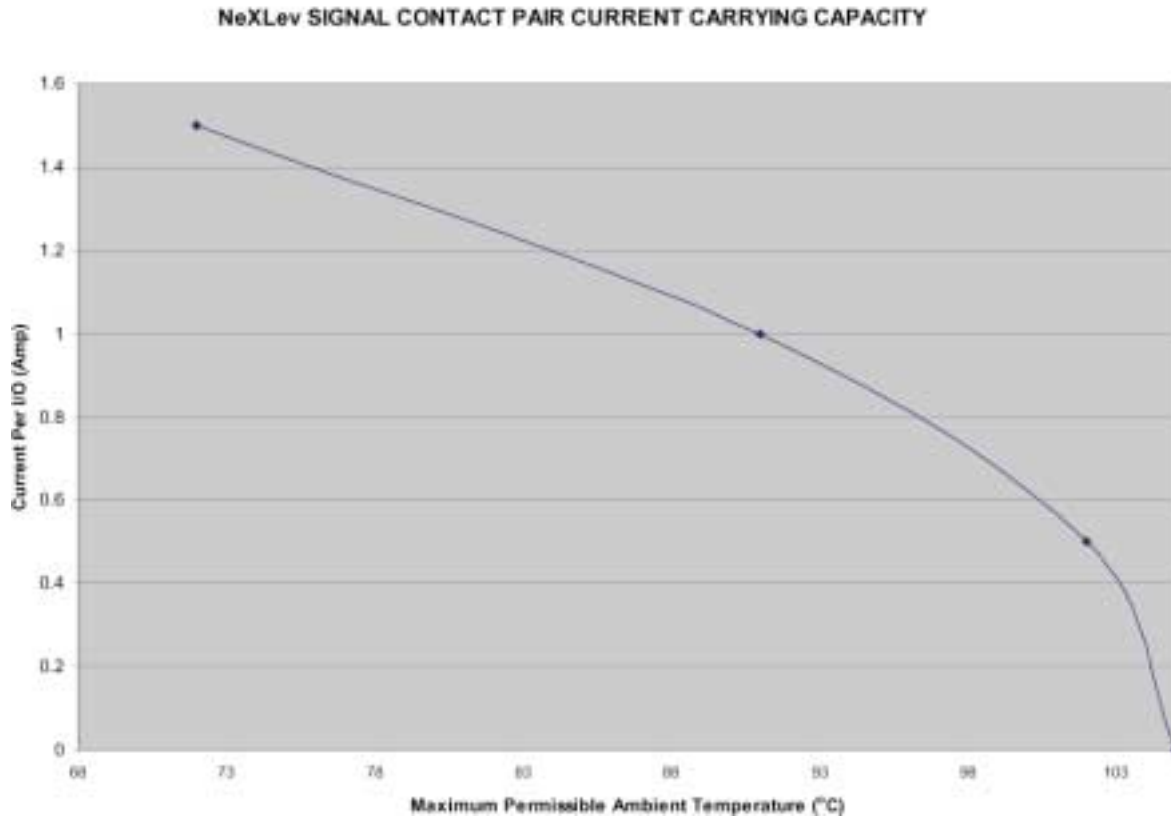


Figure 2



Figures 3 and 4 illustrate the plots of the temperature vs. current and the current rating vs. ambient temperature for the ground shields.

Figure 3

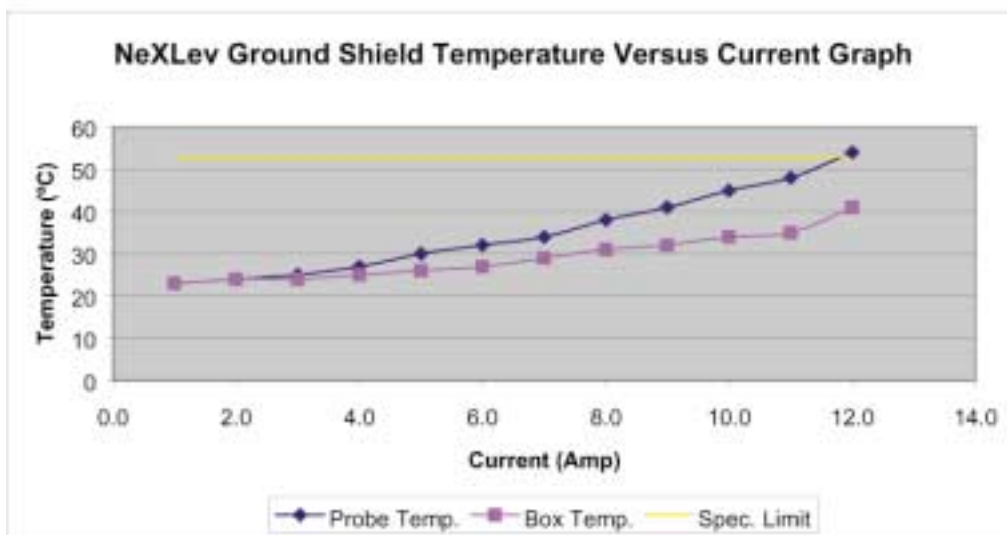


Figure 4

